

Overview

The Orion adaptor boards are designed by Future Electronics to showcase the Laird Connectivity [Sterling™-LWB+](#) and [Sterling-LWB5+](#) embedded Wi-Fi modules. The Orion design is implemented in two versions with Laird Connectivity Sterling™-LWB+ and Sterling-LWB5+ embedded Wi-Fi modules respectively, to make application development and evaluation easy. Both boards support ST Micro Nucleo-144 adaptor for easy evaluation with STM32 MCUs and MikroBus header that enables further expansion.

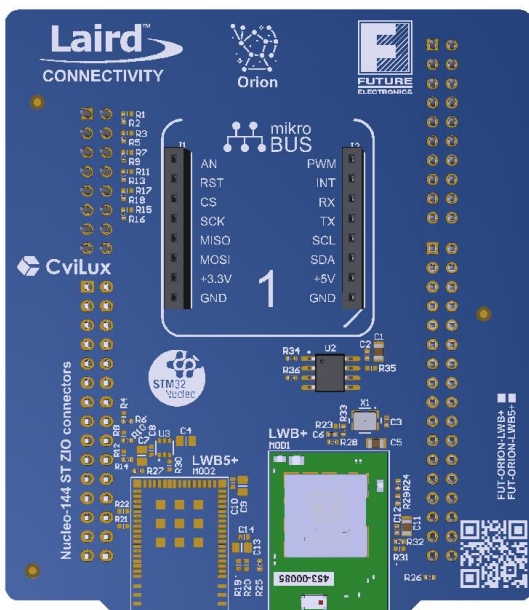
The Laird Connectivity Sterling™-LWB+ is a Wi-Fi 4 with Bluetooth 5.2 module based upon the Infineon AIROC™ [CYW43439](#) chipset. The LWB5+ series wireless module, powered by Infineon’s [CYW4373E](#) silicon, is an integrated, small form factor 1x1 SISO 802.11 a/b/g/n/ac WLAN plus dual-mode Bluetooth® 5.2 Low Energy module that is optimized for low-power mobile devices. These modules are purpose-built for industrial IoT connectivity through a secure, reliable, and robust feature set. Both modules are supported by the [Infineon’s STM32 Connectivity Expansion Pack v1.5.1](#) for STM32CubeMX tool, for ease of application development.

Features

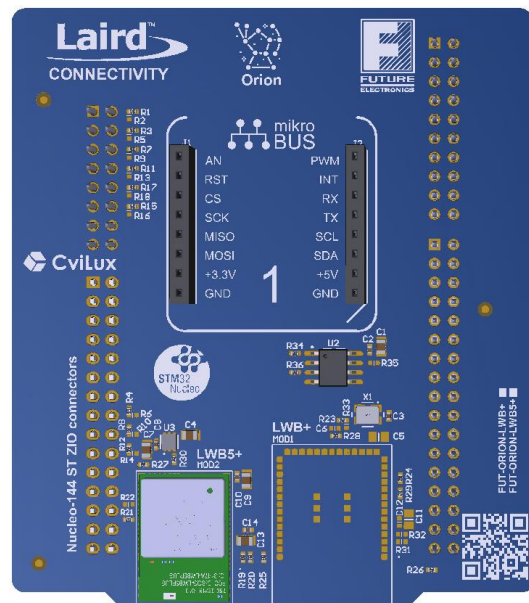
- Laird Sterling™ LWB+ or LWB5+ module
- [ST Micro Nucleo-144](#) adaptor to support the STM32 MCUs
- SPI flash on board
- MikroBus header for expansion



Board Pictures



Ordering Part Number:
[FUT-ORION-LWB+](#)



Ordering Part Number:
[FUT-ORION-LWB5+](#)